

TAPE PRESSURE BONDING APPARATUS

ABSTRACT

A tape pressure bonding apparatus includes an upper chamber, a lower chamber, a lifting mechanism that switches between a closed state in which the upper chamber is moved downward to be brought into contact with the lower chamber and an open state in which the upper chamber is separated from the lower chamber, a vacuum section that evacuates the upper chamber and the lower chamber, and an atmosphere opening section that opens the upper chamber and the lower chamber to the atmosphere. The lower chamber accommodates a wafer table that has a holding surface including a circular recess for supporting only a peripheral surplus region of the wafer and making a device region in a non-contact state. The tape pressure bonding apparatus includes a positive pressure generating section that supplies air into the circular recess of the wafer table to establish a positive pressure state in the circular recess.

[FIG.3]